Electronic Patent Application Fee Transmittal								
Application Number:	105	10581395						
Filing Date:								
Title of Invention:	Chip scale package and method of assembling the same							
First Named Inventor/Applicant Name:	Hien Boon Tan							
Filer:	Carl Joseph Pellegrini/ruth swanson							
Attorney Docket Number:	Q78657							
Filed as Large Entity								
U.S. National Stage under 35 USC 371 Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Oath/decl > 30 months from priority date		1617	1	130	130			
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 2 months with \$0 paid	1252	1	460	460
Miscellaneous:				
	Tota	590		